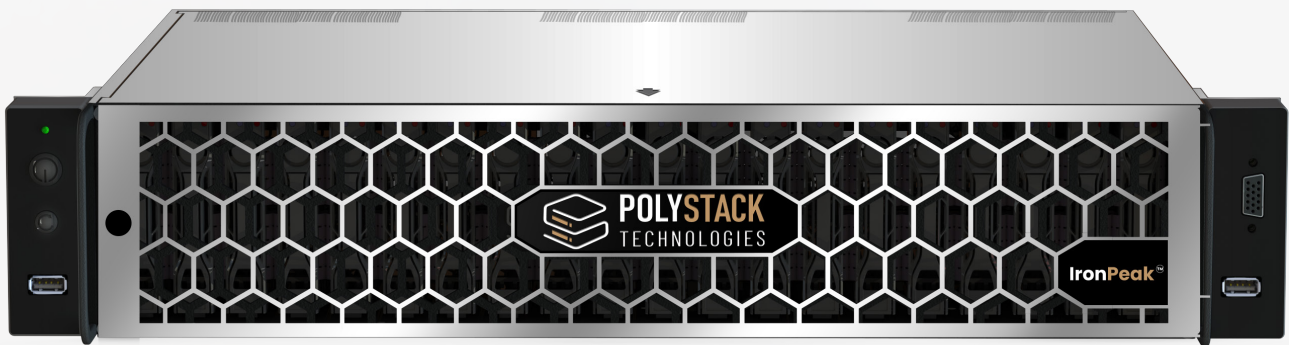




IP-IR-624-GK

KEY HIGHLIGHTS

- ▶ 2U Rackmount with 1+1, 80-PLUS Platinum, 1600W CRPS
- ▶ Intel Xeon 4th Generation Series Processor
- ▶ 24 DIMM slots supports DDR5 RDIMM, RDIMM-3DS
- ▶ 24 hot-swap 2.5" SATA/SAS
- ▶ Support 2 x M.2 Connector (PCIe Gen3), support 2280
- ▶ 6x PWM 60x56 mm fans
- ▶ Support 1 x OCP3 Gen5 x8 (CPU0) - Support 1 x OCP3
- ▶ Gen5 x16 (CPU1)
- ▶ 1 RJ45(1GbE) for BMC Management





SPECIFICATIONS

System	
Form Factor	2U Rackmount
Dimensions	770.0 X 438.0 X 87.0 mm (30.3" x 17.2" x 3.4")
Support MB	KPSRV242UAE91L
Front Panel	
Buttons	1x Power, 1x Reset, 1x UID
LEDs	1x Power, 1x UID, 1x LAN 1/2, 1x HDD Activity, 1x System status
I/O Ports	1x Type-A (USB3.0), 1x Type-A (USB2.0), 1x D-SUB (VGA)
External Drive Bay / Storage	
Front Side Drive Bay	24 hot-swap 2.5" SATA/SAS
Front Side Backplane	Support SFF 24 x SATA/SAS *(with RAID)
Rear Side Backplane	2.5" 2 x SATA/SAS RAID
Internal Side	Support 2 x M.2 Connector (PCIe Gen3, support 2280 only)
Power Supply	
Type	1+1 Redundant CRPS
Output Watts	1600W
Efficiency	Climate Saver 3 / 80Plus Titanium
System Fan	
Fan	6x PWM 60x56 mm fans
Processor System	
CPU	Intel Xeon 4th Generation Series Processor
Socket	Dual Socket SP5 (LGA 6096)
Thermal Design Power	Up to 360W
Chipset	System on Chip
System Memory	
Supported DIMM Quantity	12+12 DIMM slots (1DPC)
Supported Type	Support DDR5 288-pin RDIMM, RDIMM-3DS
Max. Capacity per DIMM	RDIMM:64GB(2R) (by condition)
Max. DIMM Frequency	4800 MHz
Voltage	1.1V
PCIe Expansion Slots	
Slot 2, Slot 3, Slot 4, Slot6	-Support 2 x FHFL PCIe Gen5 x16 -Support 2 x FHHL PCIe Gen5 x8



SPECIFICATIONS

Ethernet	
Additional GbE Controller	E810-XXVDA2
OCP slot	Support 1 x OCP3 Gen5 x8 (CPU0) - Support 1 x OCP3 Gen5 x16 (CPU1)
Server Management	
BMC Controller	ASPEED AST2600
IPMI Dedicated GLAN	1 Realtek RTL8211F for dedicated management GLAN
Graphics	
Controller	ASPEED AST2600
VRAM	DDR5 256MB
Rear I/O	
UID Button/LED	1x UID button w/ LED
VGA Port	1x MINI DP Port
USB 3.2 Gen1 Port	2x Type-A (USB3.0)
RJ45	1x RJ45(1GbE) for BMC Management
System BIOS	
BIOS Type	AMI UEFI BIOS; 256 Mb SPI Flash ROM
BIOS Features	ACPI 6.4 and above compliance wake up events, SMBIOS 3.5.0 and above, Plug and Play (PnP)
Environment	
Temperature	Operation temperature: 5°C ~ 35°C / Non operation temperature: -40°C ~ 70°C
Humidity	Non operation humidity: 20% ~ 95% (Non condensing)

APPLICATIONS



**Artificial
Intelligence**



**High Performance
Computing**



**Data
Centers**



**Cloud
Computing**



Polystack Technologies Pvt. Ltd.
1612, Office Tower, Logix City Centre
Sector-32, Noida, UP- 201301



sales@polystack.tech



www.polystack.tech



polystack.tech